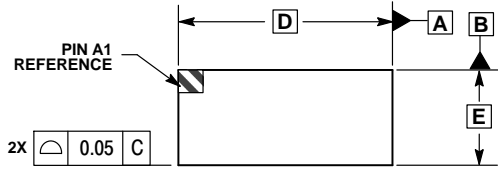


WLCSP15, 2.36x1.05
CASE 567CM 01
ISSUE O

DATE 26 JUL 2010

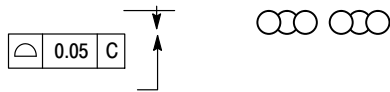


NOTES:

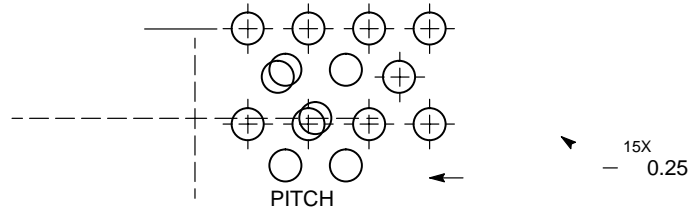
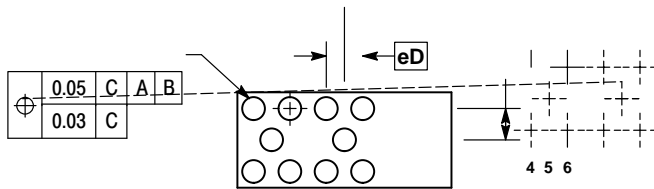
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

MILLIMETERS		
DIM	MIN	MAX
A	0.22	0.30
A1		

b	0.23	0.28
D	2.36 BSC	
E		
eD	0.400 BSC	



SEATING PLANE



DIMENSIONS: MILLIMETERS

*For additional information on our Pb Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.